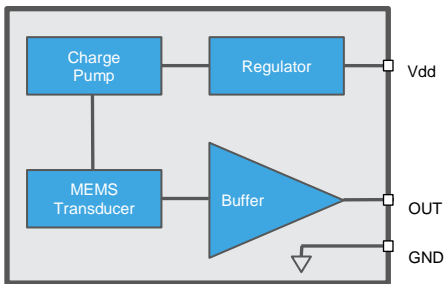


ANALOG BOTTOM PORT SISONIC™ MICROPHONE



The SPV08A0LR5H-1 is a miniature, high-performance, low power, matched sensitivity bottom port silicon microphone. Using Knowles' proven high performance SiSonic™ MEMS technology, the SPV08A0LR5H-1 consists of an acoustic sensor, a low noise input buffer, and an output amplifier. These devices are suitable for applications such as cellphones, smart phones, laptop computers, sensors, digital still cameras, portable music recorders, and other portable electronic devices where excellent wideband audio performance and RF immunity are required.

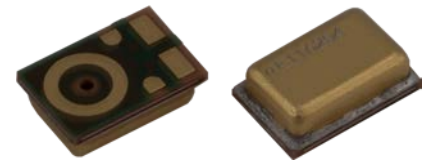


ABSOLUTE MAXIMUM RATINGS

Table 1: Absolute Maximum Ratings

| Parameter | Absolute Maximum Rating | Units |
|-----------------------|-------------------------|-------|
| Vdd to Ground | -0.3, +5.0 | V |
| OUT to Ground | -0.3, Vdd+0.3 | V |
| Input Current | ±5 | mA |
| Storage Temperature | -40 to +100 | °C |
| Operating Temperature | -40 to +85 | °C |

Stresses exceeding these "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation at these or any other conditions beyond those indicated under "Acoustic & Electrical Specifications" is not implied. Exposure beyond those indicated under "Acoustic & Electrical Specifications" for extended periods may affect device reliability.



PRODUCT FEATURES

- Matched Sensitivity
- Small Package Size
- Flat Frequency Response
- Low Current
- RF Shielded
- Bottom Port
- Ultra-Stable Performance
- Omnidirectional
- Standard SMD Reflow
- LGA Package

TYPICAL APPLICATIONS

- Headsets
- Portable electronics
- Cellphones
- Laptop Computers
- Tablets
- Portable Music Recorders



ACOUSTIC & ELECTRICAL SPECIFICATIONS¹

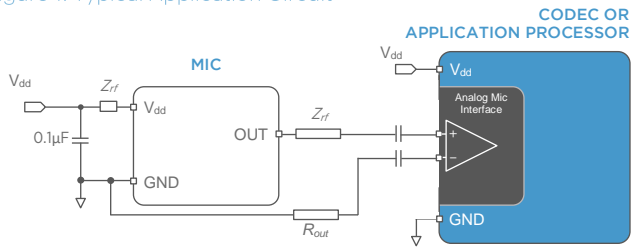
Table 2: General Microphone Specifications

Test Conditions: 23 ±2°C, 55±20% R.H., Vdd=2.75V, no load, unless otherwise indicated

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
|------------------------------|--------|--|---------------------------|------|-------|--------|
| Supply Voltage | Vdd | | 2.3 | 2.75 | 3.6 | V |
| Supply Current | Idd | Vdd = 3.6 V | - | 180 | - | µA |
| | | Vdd = 2.75 V | - | 175 | 200 | |
| Sensitivity | S | 94 dB SPL @ 1 kHz | -43 | -42 | -41 | dBV/Pa |
| Signal to Noise Ratio | SNR | 94 dB SPL @ 1 kHz, A-weighted | - | 64.5 | - | dBV/Pa |
| Near-Ultrasonic SNR | | 94 dB SPL, @ 19 kHz, BW = 18.5 - 20.0 kHz | - | 76 | - | dB |
| Total Harmonic Distortion | THD | 94 dB SPL @ 1 kHz | - | 0.05 | - | % |
| | | 115 dB SPL @ 1 kHz | - | 0.1 | - | |
| | | 1% THD @ 1 kHz, S = typ | - | 132 | - | dB SPL |
| Acoustic Overload Point | AOP | 10% THD @ 1 kHz, S = typ | - | 134 | - | dB SPL |
| Low Frequency Rolloff | LFRO | -3dB relative to 1 kHz | - | 35 | - | Hz |
| High Frequency Flatness | | +3dB relative to 1 kHz | - | 21 | - | kHz |
| Resonant Frequency Peak | Fres | | - | 42 | - | kHz |
| Power Supply Rejection Ratio | PSRR | 200 mVpp sinewave @ 1 kHz, Single-Ended Mode | - | 83 | - | dB |
| Power Supply Rejection | PSR+N | 200 mVpp 7/8 duty cycle rectangular waveform @ 217 Hz, Vdd = 2.75V, A-weighted, Single-Ended | - | -103 | - | dBV(A) |
| DC Output | | Vdd = 2.3 V | - | 0.94 | - | V |
| Output Impedance | Zout | @ 1 kHz | - | 300 | 400 | Ω |
| Output Load | Cload | | - | - | 230 | pF |
| | Rload | AC-coupled | 7 | - | - | kΩ |
| Sensitivity Drop | | Vdd(min) ≤ Vdd ≤ Vdd(max) | - | - | ±0.25 | dB |
| Directivity | | | Omnidirectional | | | |
| Polarity | | Increasing sound pressure | Increasing Output Voltage | | | |
| Startup Time | | S within 1 dB of final value, outputs AC coupled | - | - | 15 | ms |

¹ Sensitivity and Supply Current are 100% tested.

Figure 1: Typical Application Circuit



NOTES:

If necessary to improve RF performance, optional series components (resistors, ferrites, etc.) should be placed closest to the microphone pads.
Bypass capacitors should be placed near each Vdd pin for best performance.
Capacitors near the microphone should not contain Class 2 dielectrics due to their piezoelectric effect.
Follow the codec manufacturer's recommendations for circuitry and layout.

PERFORMANCE CURVES

Test Conditions: 23 ±2°C, 55±20% R.H., Vdd=2.75V, no load, unless otherwise indicated

Figure 2: Typical Free Field Magnitude Response and Masks

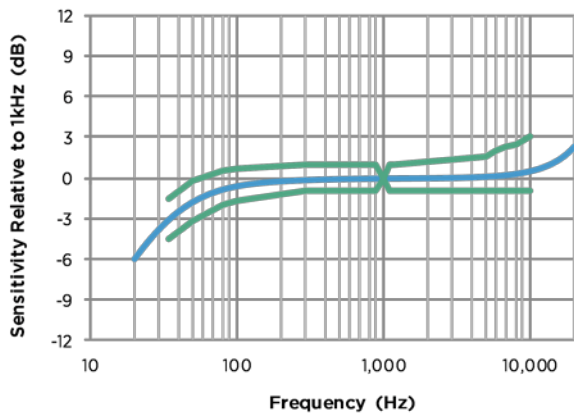


Figure 3: Typical Phase and Group Delay

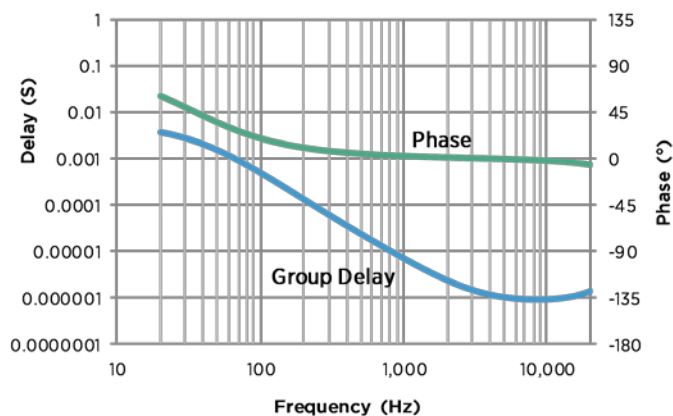


Figure 4: Typical THD vs SPL

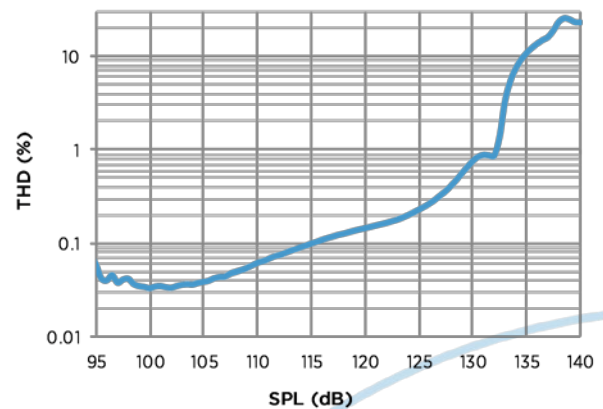


Figure 5: Typical THD vs Frequency

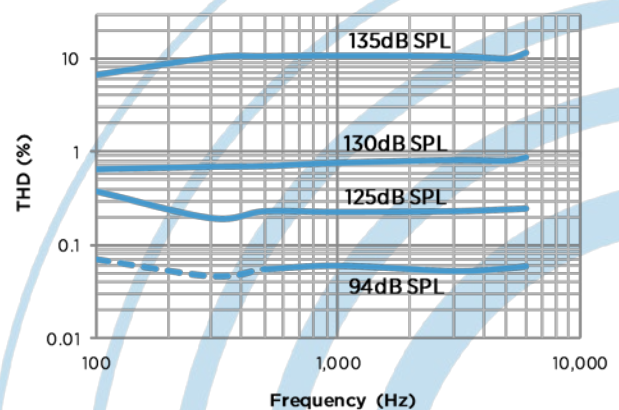


Figure 6: Typical Free Field Ultrasonic Response

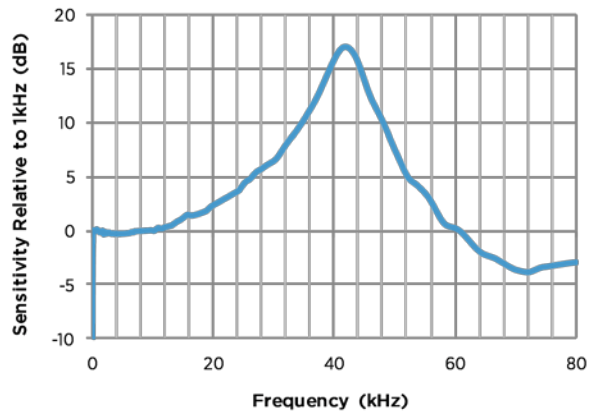


Figure 8: Noise Floor Power Spectral Density

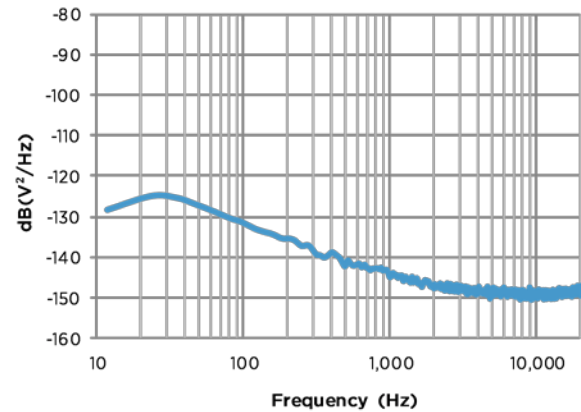


Figure 7: Typical Idd vs Vdd

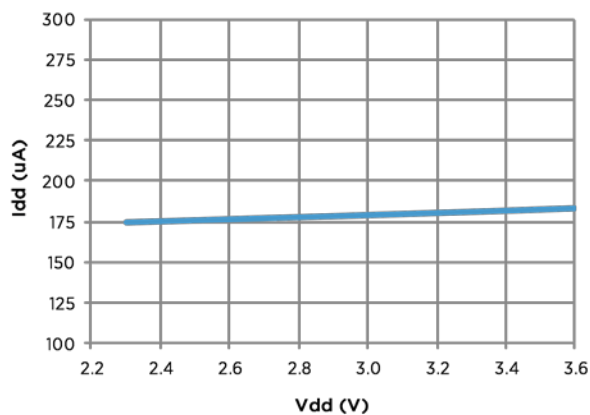
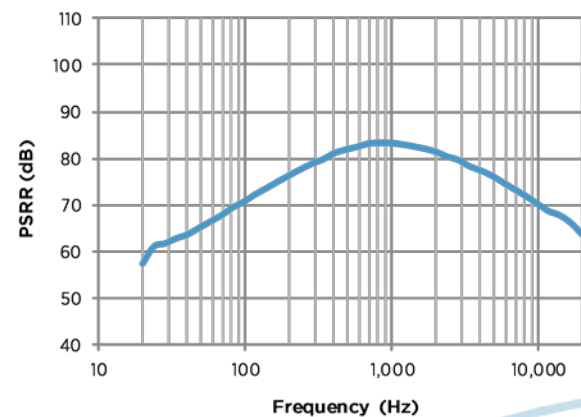


Figure 9: Typical PSRR



Technical drawing of a 1.563 inch diameter metal ring, showing three views: Top View, Side View, and Front View.

Top View Dimensions:

- Outer Diameter: 1.563 ± 0.080
- Inner Diameter: 0.875 ± 0.100 I.D. METAL RING
- Width (W): 1.652 ± 0.080
- Height (H): 2.553 ± 0.080
- Thickness (T): 0.150 ± 0.080
- Corner Radius: $R0.200 \pm 0.080$
- Feature 1: PICK AREA
- Feature 2: $2X \ 0.650 \pm 0.080$
- Feature 3: $2X \ 0.125 \pm 0.080$
- Feature 4: $2X \ 0.350 \pm 0.080$
- Feature 5: $2X \ 0.438 \pm 0.080$
- Feature 6: $2X \ R0.163$
- Feature 7: $\phi 0.950 \pm 0.080$
- Feature 8: $\phi 1.450 \pm 0.080$
- Feature 9: $\phi "AP"$

Side View Dimensions:

- Height (H): 2.553 ± 0.080
- Thickness (T): 0.150 ± 0.080

Front View Dimensions:

- Outer Diameter: 1.563 ± 0.080
- Inner Diameter: 0.875 ± 0.100 I.D. METAL RING
- Feature 1: $2X \ 0.650 \pm 0.080$
- Feature 2: $2X \ 0.125 \pm 0.080$
- Feature 3: $2X \ 0.350 \pm 0.080$
- Feature 4: $2X \ 0.438 \pm 0.080$
- Feature 5: $2X \ R0.163$
- Feature 6: $\phi 0.950 \pm 0.080$
- Feature 7: $\phi 1.450 \pm 0.080$
- Feature 8: $\phi "AP"$
- Feature 9: 0.925 ± 0.100 I.D. METAL RING

Feature Control Table:

| Feature | Symbol | Value | Feature | Symbol | Value |
|---------|----------|--------------|---------|--------|-------|
| 1 | \oplus | $\phi 0.100$ | A | B | C |

| Item | Dimension | Tolerance |
|--------------------|-----------|------------------|
| Length (L) | 2.75 | ±0.10 |
| Width (W) | 1.85 | ±0.10 |
| Height (H) | 0.90 | ±0.10 |
| Acoustic Port (AP) | Ø0.25 | ±0.05 |
| PCB Thickness (T) | 0.285 | -0.035, +0.05 |

| Pin # | Pin Name | Type | Description |
|-------|------------|--------|---|
| 1 | Vdd | Power | Power Supply |
| 2 | OUT | Signal | Output |
| 3 | GROUND | Power | Ground |
| 4, 5 | No Connect | N/A | Test Pin - do not place over ground plane |

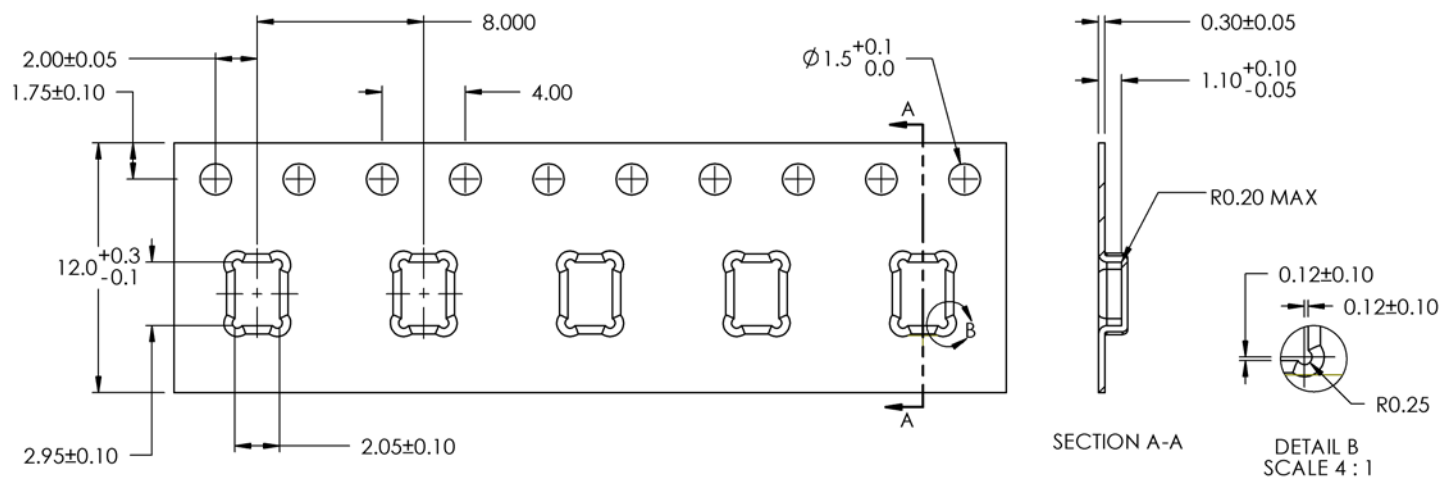
Technical drawing of a mechanical part with dimensions:

- Top view dimensions:
 - Horizontal distance from center to first hole: 0.150
 - Horizontal distance between holes: 2X 0.650
 - Horizontal distance from second hole to center: 0.150
 - Vertical distance from center to first hole: 2X 0.350
 - Vertical distance from center to second hole: 2X 1.400
- Bottom view dimensions:
 - Outer diameter: $\varnothing 1.450$
 - Inner diameter: $\varnothing 0.950$
 - Radial thickness of each segment: 4X 0.200

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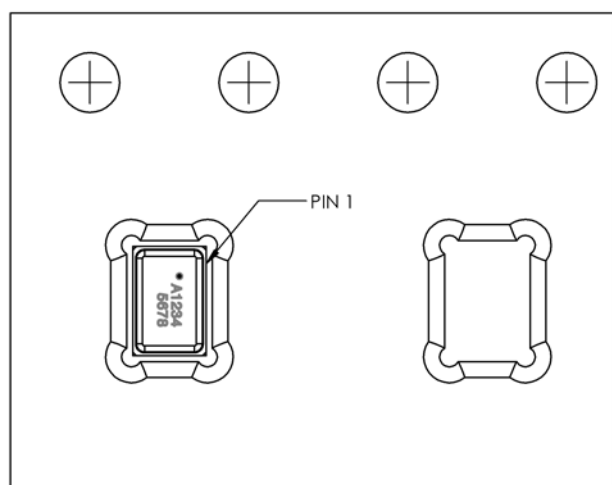


PACKAGING & MARKING DETAIL



| Model Number | Suffix | Reel Diameter | Quantity Per Reel |
|---------------|--------|---------------|-------------------|
| SPV08A0LR5H-1 | -8 | 13" | 5,900 |

| Component | Surface Resistance (ohms) |
|--------------|---------------------------|
| Reel | $10^5 - 10^9$ |
| Carrier Tape | $10^5 - 10^9$ |
| Cover Tape | $10^4 - 10^{10}$ |



NOTES:

Dimensions are in millimeters unless otherwise specified.
Vacuum pickup only in the pick area indicated in Mechanical Specifications.
Tape & reel per EIA-481.

Labels applied directly to reel and external package.

Shelf life: Twelve (12) months when devices are stored in the factory-supplied, unopened ESD moisture sensitive bag under the maximum environmental conditions of 30°C, 70% R.H.

Alpha Character A:

"S": Knowles SiSonic™ Production

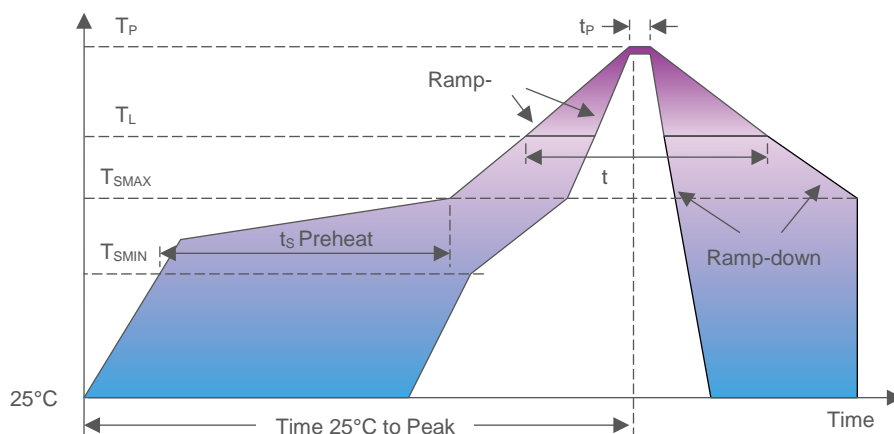
"E": Knowles Engineering Samples

"P": Knowles Prototype Samples

"12345678":

Unique Job Identification Number for product traceability

RECOMMENDED REFLOW PROFILE



| Profile Feature | Pb-Free |
|---|----------------------------------|
| Average Ramp-up rate (T _{SMAX} to T _P) | 3°C/second max. |
| Preheat <ul style="list-style-type: none"> Temperature Min (T_{SMIN}) Temperature Max (T_{SMAX}) Time (T_{SMIN} to T_{SMAX}) (t_s) | 150°C 200°C 60-180 seconds |
| Time maintained above: <ul style="list-style-type: none"> Temperature (T_L) Time (t_L) | 217°C 60-150 seconds |
| Peak Temperature (T _P) | 260°C |
| Time within 5°C of actual Peak Temperature (t _P) | 20-40 seconds |
| Ramp-down rate (T _P to T _{SMAX}) | 6°C/second max |
| Time 25°C to Peak Temperature | 8 minutes max |

NOTES:

Based on IPC/JDEC J-STD-020 Revision C.

All temperatures refer to topside of the package, measured on the package body surface.

The actual reflow profile used should be optimized based on the reflow requirements of all components, board design, solder paste formulation and reflow equipment used. Details of recommended handling and manufacturing processes can be found in AN25 SMT Manufacturing Guidelines for SiSonic™ Microphones.

ADDITIONAL NOTES

- (A) MSL (moisture sensitivity level) Class 1.
- (B) Maximum of 3 reflow cycles is recommended.
- (C) In order to minimize device damage:
- Do not board wash or clean after the reflow process.
 - Do not brush board with or without solvents after the reflow process.
 - Do not directly expose to ultrasonic processing, welding, or cleaning.
 - Do not insert any object in port hole of device at any time.
 - Do not apply over 30 psi of air pressure into the port hole.
 - Do not pull a vacuum over port hole of the microphone.
 - Do not apply a vacuum when repacking into sealed bags at a rate faster than 0.5 atm/sec.
 - Do not directly expose to vapor phase soldering.

MATERIALS STATEMENT

Meets the requirements of the European RoHS directive 2011/65/EC as amended.

Meets the requirements of the industry standard IEC 61249-2-21:2003 for halogenated substances and Knowles Green Materials Standards Policy section on Halogen-Free.

Product is Beryllium Free according to limits specified on the Knowles Hazardous Material List (HSL for Products).

Ozone depleting substances are not used in the product or the processes used to make the product, including compounds listed in Annex A, B, and C of the "Montreal Protocol on Substances That Deplete the Ozone Layer."

RELIABILITY SPECIFICATIONS

| Test | Description |
|---------------------------|--|
| Thermal Shock | 100 cycles of air-air thermal shock from -40°C to +125°C with 15 minute soaks (IEC 68-2-4) |
| High Temperature Storage | +105°C environment for 1,000 hours (IEC 68-2-2 Test Ba) |
| Low Temperature Storage | -40°C environment for 1,000 hours (IEC 68-2-1 Test Aa) |
| High Temperature Bias | +105°C environment while under bias for 1,000 hours (IEC 68-2-2 Test Ba) |
| Low Temperature Bias | -40°C environment while under bias for 1,000 hours (IEC 68-2-1 Test Aa) |
| Temperature/Humidity Bias | +85°C/85% R.H. environment while under bias for 1,000 hours (JESD22-A101A-B) |
| Vibration | 12 minutes in each X, Y, Z axis from 20 to 2,000 Hz with peak acceleration of 20 G (MIL 883E, Method 2007.2,A) |
| ESD-HBM | 3 discharges at ±2kV direct contact to I/O pins (MIL 883E, Method 3015.7) |
| ESD-LID/GND | 3 discharges at ±8kV direct contact to lid when unit is grounded (IEC 61000-4-2) |
| ESD-MM | 3 discharges at ±200V direct contact to IO pins (ESD STM5.2) |
| Reflow | 5 reflow cycles with peak temperature of +260°C |
| Mechanical Shock | 3 pulses of 10,000 G in each of the X, Y, and Z directions (IEC 68-2-27 Test Ea) |

NOTES:

Microphones meet all acoustic and electrical specifications before and after reliability testing, except sensitivity which can deviate up to 3dB.

After 3 reflow cycles, the sensitivity of the microphones shall not deviate more than 1 dB from its initial value.

SPECIFICATION REVISIONS

| Revision | Specification Changes | Date |
|----------|--|---------|
| A | Initial Release (ECR 18-2432) | 6/20/18 |
| B | Update Rmin (AC-coupled) value (ECR 19-3046) | 4/25/19 |
| C | Updated max Cload value and added comment on vapor phase soldering (ECR 19-3150) | 6/18/19 |
| D | Add Frequency Response Masks (ECR 20-3632) | 3/13/20 |
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